

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4648184

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHIHO WADA	09/26/2017
RECEIVING PARTY DATA	
Name:	NITTO DENKO CORPORATION
Street Address:	1-2, SHIMOHUZUMI 1-CHOME, IBARAKI-SHI,
City:	OSAKA
State/Country:	JAPAN
Postal Code:	567-8680
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15567678
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NAME OF SUBMITTER:	DANIEL B. MOON
SIGNATURE:	/Daniel B. Moon/
DATE SIGNED:	10/19/2017
Total Attachments: 2	
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Docket No.

ASSIGNMENT OF PATENT APPLICATION

WHEREAS,

1. Shiho WADA residing at c/o NITTO DENKO CORPORATION, 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka 567-8680 Japan and a citizen of Japan

(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on _____, entitled FILTER MEDIUM AND FILTER UNIT, and which has been given application serial number _____ ;

and

WHEREAS NITTO DENKO CORPORATION (hereinafter "ASSIGNEE") a corporation organized under the laws of Japan and having an office and place of business at 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka 567-8680 Japan wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEE, its successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all Letters Patent for said invention to the ASSIGNEE of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the

rights and property herein conveyed has been or will be made to others by the
UNDERSIGNED, and that full right to convey the same as herein expressed is possessed
by the UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on
the dates indicated below.

Shino Wada
Signature

September 26, 2017
Date